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Impact of Process Variations on Low Power Cache Design

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Introduction

- Process variations increase as the feature reduces due to the difficulty of fabricating small structures consistently across a die or wafer.
- In order to analyze the delay and power consumption of a cache under process variation, we must consider both inter-die and intra-die variation
 - Intra-die variations are the variations in device parameters within a single chip, which means different devices at different locations on a single die may have different device features
 - Inter-die variations are the variations that occur from one die to the other, from wafer to wafer, and from wafer lot to wafer lot
- Two main sources of variation:
 - Physical factors
 - Environmental factors

Introduction

- The physical factors are permanent and result from limitations in the fabrication process
 - Effective Channel Length (Geometric Variations):
 - Imperfections in photolithography
 - Variations in *Leff* can be as high as 50% within a die
 - Threshold Voltage (Electrical Parameter Variation):
 - Variation in device geometry

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- Variations in *Vth* can be modeled as 10% of Vth of the smallest device in a given technology [A. Chandrakasan et al., IEEE press 2001]
- The environmental factors depend on the operation of the system and include variations in:
 - Temperature, Power Supply, Switching Activity

Impact of Process Variations on Caches

- The parameter variations are random in nature and are expected to be more pronounced in minimum geometry transistors commonly used in memories.
- Caches in processors like UltraSPARC III, Itanium 2, StorngARM110, and Alpha 21164 can occupy more than 50% of die area.
- Process variations impact the components of a memory subsystem:
 - SRAM Cell

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- Sense Amplifier
- Address Decoder
- Can cause failure in data access
 - E.g., due to incorrect sensing or slow cell access

Effect of Process Variations on Delay Accessing 1-bit in SRAM Column of 32 Bit Height



The delay can increase as such as 16% per cell.

The Threshold voltage (Vth) variation can impact the delay by 30% per cell access

Worst-case Delay



The delay can increase as such as 50% combining the effects of Vth and Leff.

Effect of Process Variations on Power Consumption of 1KB SRAM



A small variation in the *Leff* value causes a change in the leakage power by as such as 40X from the nominal value.

The Threshold voltage (Vth) variation can impact the power consumption by 65X

Vth(V)

Cache Access Failure?

- A failure in a cell can occur due to:
 - Access Time Failure (due to increase in the access time)
 - Read Stability Failure
 - Write Stability Failure
 - Hold Failure
- \circ $\,$ Failure Probability of a Read $\,$
 - E.g., the minimum differential voltage required for correct sensing (Taccess in figure) needs to be < Tmax for a correct read
 - Threshold voltage distributions are approximated as Gaussian





[Classification is take from S. Mukhopadhyay, et al. Symposium on VLSI Circuits, June 2004]

Failure in Sense Amplifiers

• Circuits like differential sense amplifiers are affected

 Changing offset voltage may lead to erroneous behavior (e.g., due to access Transistors MN3 and MN3B).



What About Application Performance?



[simplescalar simulations]

 To account for the worst case scenario we might need to increase the cache access time

Performance
 impact as much as
 30-40% in the
 example on the
 left

Possible Architectural Directions

- How do we design caches that work in face of these problems?
- We can select a cache design using worst case assumptions
 - ALL VARIATIONS and ALL COMPONENTS on the critical path
- Alternatively, we need to design circuits and architectures that would work *adaptively* depending on actual delay
 - Process variation resilient design
 - Resilience against delays in different parts of the cache

Our Choice: An Adaptive Process Resilient Cache Architecture

- Two phases of operation: classifying and execution
- Classifying phase
 - The cache is equipped with a built-in-self-test (BIST) to detect speed difference due to process variation.
 - Each cache line is tested using BIST when the test mode signal is on. A block is considered fast, medium, or slow (this is for the sake of an example).



An Adaptive Process Resilient Cache Architecture

- Since the speed of the accessed cells (cache lines) changes depending on operating condition (e.g., supply voltage, frequency), such tests are conducted whenever there is a change in operating condition.
 - BIST feeds this information into the delay storage.
- o Execution phase
 - The speed information stored in the delay storage is used to control sense amplifiers during regular operations of the circuit.



Circuit Level Support: Double Sensing

- We need a mechanism to avoid sensing prematurely
- The basic idea of double sensing is to have parallel sense amplifiers to sample the bitline twice during a read cycle. This is required in an adaptive cache design with different cache line latencies.
- The first sensing is performed as the conventional one. The second sensing is delayed and has to be fired as late as required.



Preliminary Results

Baseline: 3 cycle D-cache. Out of order issue.
Adaptive caching scheme: e.g., 3% 3 cycle, 12% 2 cycle. 85% 1 cycle cache line access.
Results below show performance is improved by 13% to 29%!



Conclusion

- Parameter variations will become worse with technology scaling.
- Robust variation tolerant circuits and architectures needed.
- We have shown that process variation can have a significant impact on delay (expected > 2X with all factors included), and in worst-case leads to timing violations.
- In addition, power dissipation, especially leakage power has been shown to be significantly affected (>60X) by the parameter variations.
- Shown new resilient cache architecture